

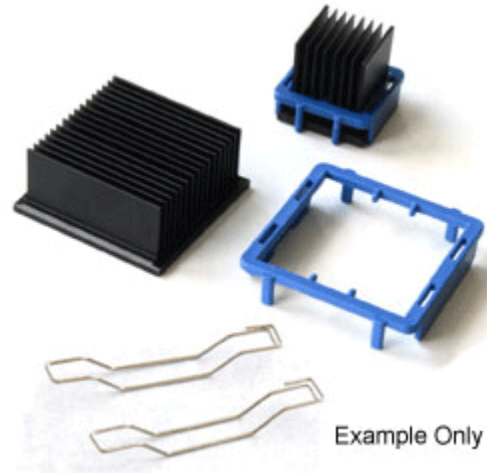


BOARD LEVEL COOLING - EA-330

EA-330 is a series of clip attach bi-directional square board level heat sinks designed to cool BGA and FPGA devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
EA-330-H095-T710	BGA, FPGA
EA-330-H125-T710	BGA, FPGA
EA-330-H145-T710	BGA, FPGA
EA-330-H175-T710	BGA, FPGA
EA-330-H195-T710	BGA, FPGA
EA-330-H225-T710	BGA, FPGA
EA-330-H245-T710	BGA, FPGA



HEAT SINK DETAILS

Property	Details
Material	Aluminum, Plastic
Finish	Black Anodize
Device Attachment Options	Clip Attachment
Thermal Interface Material	Chomerics T710 Phase Change Material

Property	Details
Heat Sink Width (mm)	33.0
Heat Sink Length (mm)	33.0
Heat Sink Height (mm)	See Table
Heat Sink Mounting Direction	Horizontal, Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm

Part Number	Heat Sink Height
EA-330-H095-T710	9.5
EA-330-H125-T710	12.5
EA-330-H145-T710	14.5
EA-330-H175-T710	17.5
EA-330-H195-T710	19.5
EA-330-H225-T710	22.5
EA-330-H245-T710	24.5

